

Serial No.: 10/500,128

### LIST OF PENDING CLAIMS

20. (Currently Amended) A curable adhesive composition for anchoring materials in or to concrete or masonry comprising:

an encapsulated first part including an epoxy resin comprising at least one polymerizable epoxy compound; and

a reactive diluent incorporated into the epoxy compound, the reactive diluent having at least one reactive terminal end portion, the epoxy compound and the reactive diluent having a weight ratio of 65:10 to 90:0.5; and

a separately encapsulated second part including a curing agent comprising at least one aliphatic amine and at least one tertiary amine;

wherein said adhesive composition has an epoxy:amine weight ratio of about 0.5:1 to about 10:1 and passes the ICBO Heat Creep Test (ICBO Acceptance Criteria AC58) at 110°F and passes the ICBO Damp Hole Test at 75°F.

21. (Previously Presented) The curable adhesive composition of claim 20 wherein said curing agent comprises a plurality of aliphatic amines including a first aliphatic amine having an amine value of about 400 mg KOH/g to about 500 mg KOH/g and a second aliphatic amine having an amine value greater than about 550 mg KOH/g.

22. (Previously Presented) The curable adhesive composition of claim 21 wherein said second aliphatic amine has an amine value of about 550 mg KOH/g to about 700 mg KOH/g.

23. (Previously Presented) The curable adhesive composition of claim 22 wherein said first and second aliphatic amines have a glass transition temperature of about 130°F to about 135°F.

24. (Previously Presented) The curable composition of claim 21 wherein said aliphatic amines and said one or more tertiary amines are respectfully present in a weight of about 15:1 to about 25:1.

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25. (Previously Presented) The curable adhesive composition of claim 20 wherein said curing agent is present in an amount of about 5 to about 50 weight percent.

26. (Previously Presented) The curable adhesive composition of claim 20 wherein said curing agent is present in an amount of about 20 parts by weight of active components (pbwa) to about 50 pbwa.

27. (Previously Presented) The curable adhesive composition of claim 21 wherein said curing agent consists of said plurality of aliphatic amines and said at least one tertiary amine.

28. (Previously Presented) The curable adhesive composition of claim 20 wherein said polymerizable epoxy compound is derived from the reaction of difunctional bisphenol-A and epichlorhydrin.

29. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound has an epoxide equivalent weight of from about 180 to about 190.

30. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound is present in the adhesive composition in an amount of about 20 weight percent to about 40 weight percent.

31. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound is present in the adhesive compositions in an amount of about 70 parts by weight of active components (pbwa) to about 95 pbwa.

Claims 32-34 (Canceled)

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35. (Previously Presented) The adhesive composition of claim 20 wherein said reactive diluent is 1, 4-cyclohexane-dimethanol diglycidyl ether.

Claim 36 (Canceled)

37. (Previously Presented) The adhesive composition of claim 20 having a cure time of no greater than about 2.5 hours.

38. (Previously Presented) The adhesive composition of claim 23 wherein said first aliphatic amine and said second aliphatic amine are present in a weight ratio of about 1:1 to about 3:1.

39. (Currently Amended) A curable adhesive composition for anchoring materials in or to concrete or masonry comprising:

an encapsulated first part including an epoxy resin comprising at least one difunctional polymerizable liquid epoxy compound; and

a reactive diluent incorporated into the epoxy compound, the reactive diluent having at least one reactive terminal end portion including an epoxy group, the epoxy compound and the reactive diluent having a weight ratio of 65:10- to 90:0.5; and

a separately encapsulated second part including a curing agent comprising at least one aliphatic amine and at least one tertiary amine;

wherein (i) said adhesive composition has an epoxy:amine weight ratio of about 0.5:1 to about 10:1, (ii) said aliphatic amine has a glass transition temperature of from about 125°F to about 140°F and amine value of at least about 350 mg KOH/g; and (iii) said at least one tertiary amine has an amine value of from about 400 mg KOH/g to about 800 mg KOH/g.

40. (Previously Presented) The adhesive composition of claim 39 having a cure time of not greater than about 2 hours.

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41. (Previously Presented) The curable adhesive composition of claim 40 wherein said adhesive composition has an epoxy:amine weight ratio of about 0.7:1 to about 2:1.

42. (Previously Presented) The curable adhesive composition of claim 40 wherein said curing agent comprises a plurality of aliphatic amines including a first aliphatic amine having an amine value of about 400 mg KOH/g to about 500 mg KOH/g.

43. (Previously Presented) The curable adhesive composition of claim 42 wherein said second aliphatic amine has an amine value of about 550 mg KOH/g to about 700 mg KOH/g.

Claims 44-46 (Canceled)

47. (Previously Presented) The curable composition of claim 42 wherein said aliphatic amines and said at least one tertiary amine are respectively present in a weight of about 15:1 to about 25:1.

48. (Previously Presented) The curable composition of claim 42 wherein said aliphatic amines and said one or more tertiary amines are respectively present in a weight of about 20:9 to about 35:0.5.

49. (Previously Presented) The curable adhesive composition of claim 20, wherein the reactive terminal end portion of the reactive diluent includes an epoxy group.

50. (Previously Presented) The curable adhesive composition of claim 20, wherein the reactive diluent includes a cyclic backbone.

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51. (Previously Presented) The curable adhesive composition of claim 20, wherein the epoxy compound and the reactive diluent have a weight ratio in the composition of 70:5 to 80:0.5.

52. (Previously Presented) The curable adhesive composition of claim 20, wherein the epoxy compound has a viscosity of 11,000 to 14,000 centipoise at 25°C.

53. (Previously Presented) The curable adhesive composition of claim 39, wherein the reactive diluent includes a cyclic backbone.

54. (Previously Presented) The curable adhesive composition of claim 39, wherein the epoxy compound has a viscosity of 11,000 to 14,000 centipoise at 25°C.